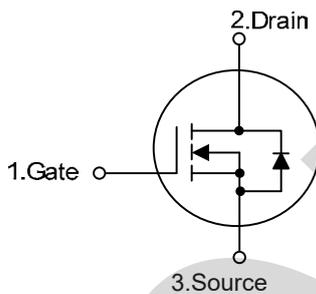
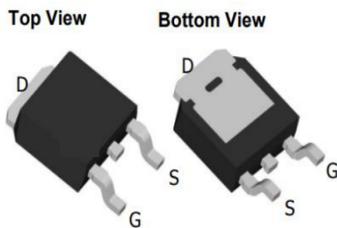


## Trench N-channel Power MOSFET

**MSR3R8N03D**

**TO-252**



$V_{DS}$	30	V
$R_{DS(on),TYP@ V_{GS}=10V}$	3.2	m $\Omega$
$I_D$	150	A

### Features

- 1、 Low on – resistance
- 2、 Package TO-252
- 3、 TrenchFET Power MOSFET

### Applications

- 1、 Load Switch for Portable Devices
- 2、 DC/DC Converter

**Maximum ratings, at TA =25°C, unless otherwise specified**

Symbol	Parameter	Rating	Unit	
$V_{(BR)DSS}$	Drain-Source breakdown voltage	30	V	
$V_{GS}$	Gate-Source voltage	$\pm 20$	V	
$I_S$	Diode continuous forward current	$T_C=25^\circ C$	--	
$I_D$	Continuous drain current @ $V_{GS}=10V$	$T_C = 25^\circ C$ (Package limit)	150	A
		$T_C = 100^\circ C$ (Silicon limit)	100	A
$I_{DM}$	Pulse drain current tested ①	$T_C=25^\circ C$	400	A
$E_{AS}$	Avalanche energy, single pulsed ②		529	mJ
$P_D$	Maximum power dissipation	$T_C=25^\circ C$	110	W
$T_{STG}, T_J$	Storage and Junction Temperature Range		-55 to +175	$^\circ C$

## Thermal Characteristics

Symbol	Parameter	Typical	Unit
R <sub>θJC</sub>	Thermal Resistance, Junction-to-Case	1.36	°C/W

## Electrical Characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
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Static Electrical Characteristics @T<sub>j</sub>=25°C (unless otherwise stated)

V(BR)DSS	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	30	--	--	V
IDSS	Zero Gate Voltage Drain Current	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V, T <sub>j</sub> =25°C	--	--	1	μA
		V <sub>DS</sub> =24V, V <sub>GS</sub> =0V, T <sub>j</sub> =125°C	--	--	10	μA
IGSS	Gate-Body Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	--	--	±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1.0	1.6	2.5	V
R <sub>DS(on)</sub>	Drain-Source On-State Resistance ④	V <sub>GS</sub> =10V, I <sub>D</sub> =30A	--	3.2	3.8	mΩ

## Dynamic Electrical Characteristics @T<sub>j</sub> = 25°C (unless otherwise stated)

C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =25V, f=1MHz	--	3400	--	pF
C <sub>oss</sub>	Output Capacitance		--	356	--	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		--	308	--	pF
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> = 5 V, I <sub>D</sub> = 24A	--	28	--	S
Q <sub>g</sub> (10V)	Total Gate Charge	V <sub>GS</sub> =10V, V <sub>DS</sub> =15V, I <sub>D</sub> =30A, f=1MHz	--	70	--	nC
Q <sub>gs</sub>	Gate-Source Charge		--	12	--	nC
Q <sub>gd</sub>	Gate-Drain Charge		--	16.3	--	nC
R <sub>G</sub>	Gate resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1MHz	--	1	--	Ω

## Switching Characteristics

Td(on)	Turn-on Delay Time	V <sub>DD</sub> =15V, I <sub>DS</sub> =30A, R <sub>L</sub> =1.8Ω, T <sub>J</sub> =25°C	--	11	--	ns
Tr	Turn-on Rise Time		--	120	--	ns
Td(off)	Turn-Off Delay Time		--	25	--	ns
Tf	Turn-Off Fall Time		--	60	--	ns

## Source -Drain Diode Characteristics @T<sub>J</sub> = 25°C (unless otherwise stated)

VSD	Forward on voltage	I <sub>SD</sub> =40A, V <sub>GS</sub> =0V	--	0.84	1.2	V
Trr	Reverse Recovery Time (Note1)	I <sub>SD</sub> =30A, V <sub>GS</sub> =0V	--	56	--	ns
Qrr	Reverse Recovery Charge (Note1)	di/dt=100A/μs	--	110	--	nC

NOTE: ① Repetitive rating; pulse width limited by max junction temperature.

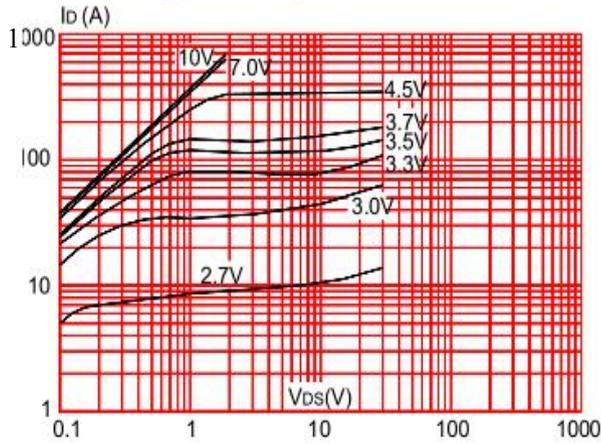
② Limited by T<sub>Jmax</sub>, starting T<sub>J</sub> = 25°C, L = 0.5mH, R<sub>G</sub> = 25Ω, I<sub>AS</sub> = 9A, V<sub>GS</sub> = 10V. Part not recommended for use above this value

③ The power dissipation P<sub>DSM</sub> is based on R<sub>θJA</sub> and the maximum allowed junction temperature of 150°C.

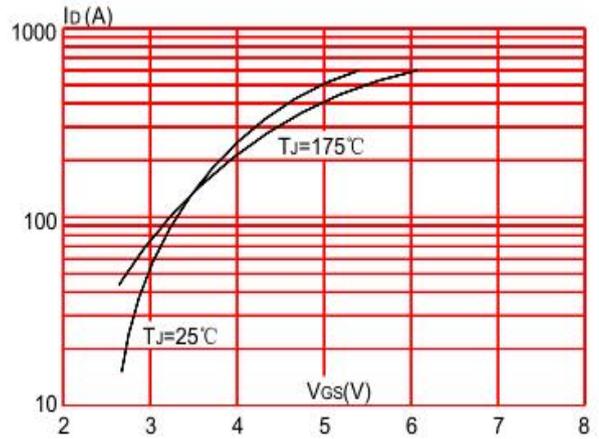
④ Pulse width ≤ 300μs; duty cycle ≤ 2%.

## Typical Characteristics

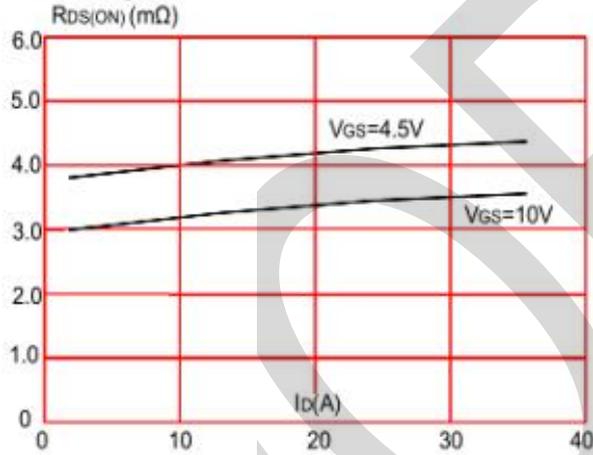
**Figure 1: Output Characteristics**



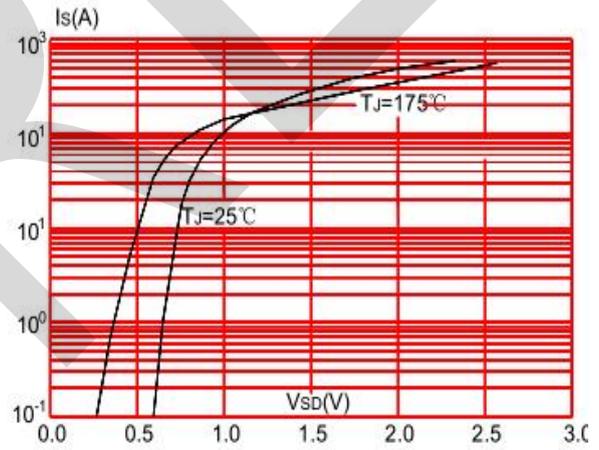
**Figure 2: Typical Transfer Characteristics**



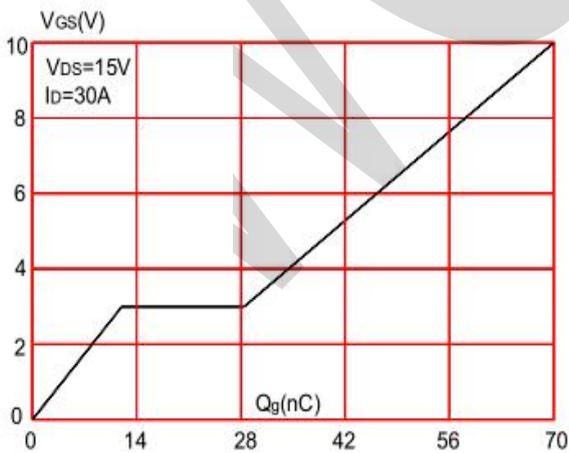
**Figure 3: On-resistance vs. Drain Current**



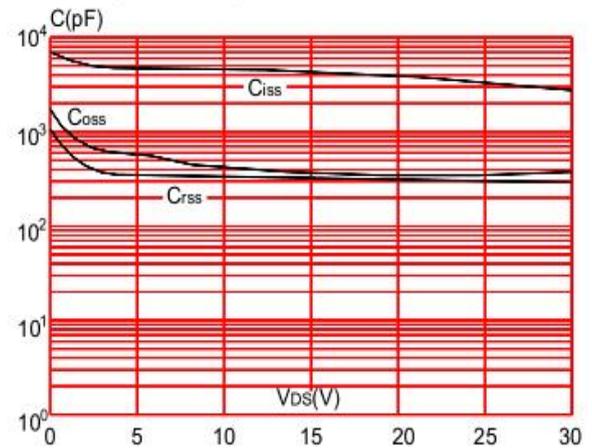
**Figure 4: Body Diode Characteristics**



**Figure 5: Gate Charge Characteristics**



**Figure 6: Capacitance Characteristics**



Typical Characteristics

Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

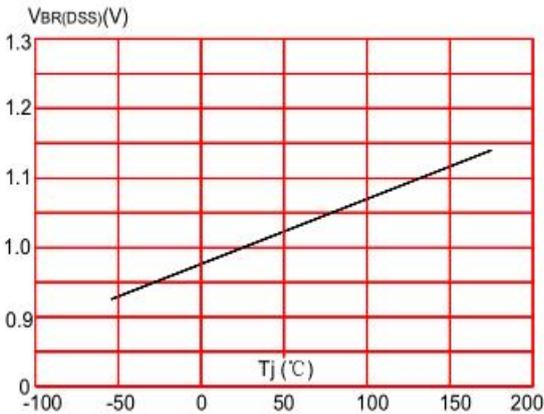


Figure 8: Normalized on Resistance vs. Junction Temperature

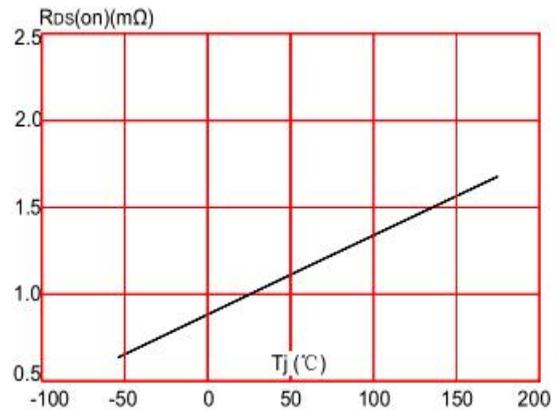


Figure 9: Maximum Safe Operating Area

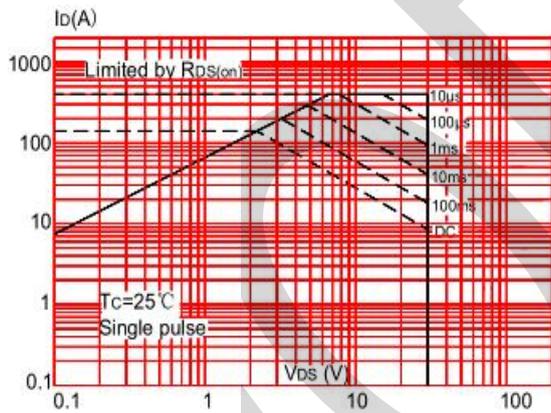


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

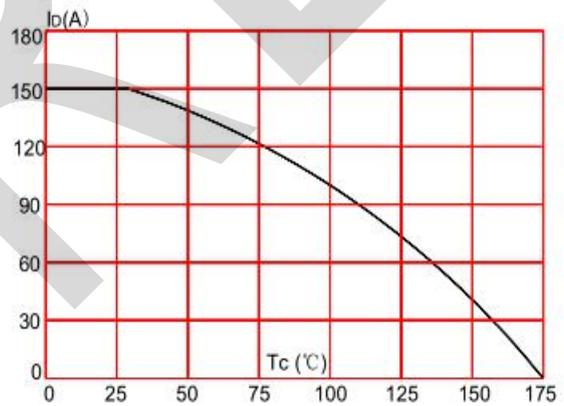


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Case (TO-252)

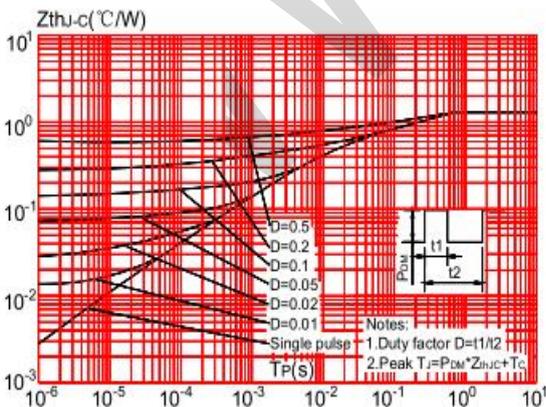
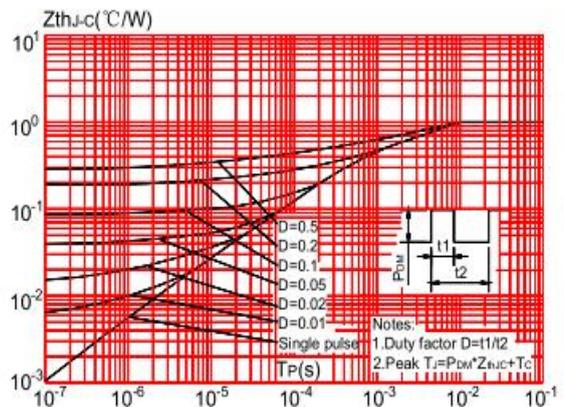


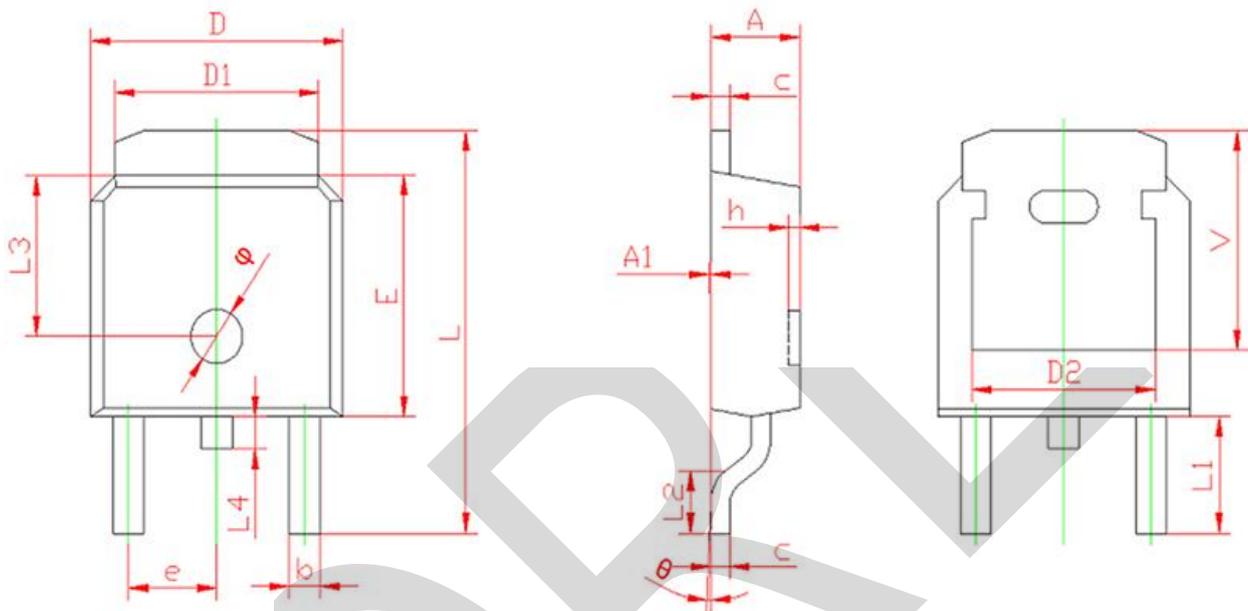
Figure.12: Maximum Effective Transient Thermal Impedance, Junction-to-Case (TO-263,TO-220C)



**PACKAGE OUTLINE DIMENSIONS**

Note:unit mm

**TO-252**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.800 REF		0.189 REF	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 REF		0.114 REF	
L2	1.400	1.700	0.055	0.067
L3	4.00 REF		0.157 REF	
L4	0.600	1.000	0.024	0.039
φ	1.200	1.400	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.500 REF		0.217 REF	

**Package : TO-252**